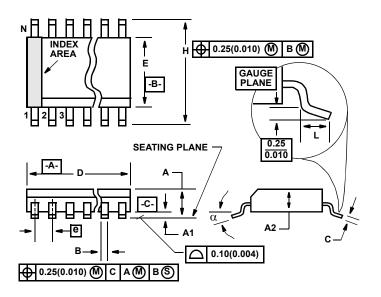
## **Plastic Packages for Integrated Circuits**

## Shrink Small Outline Plastic Packages (SSOP)



## NOTES:

- 1. Symbols are defined in the "MO Series Symbol List" in Section 2.2 of Publication Number 95.
- 2. Dimensioning and tolerancing per ANSI Y14.5M-1982.
- Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion and gate burrs shall not exceed 0.20mm (0.0078 inch) per side.
- Dimension "E" does not include interlead flash or protrusions. Interlead flash and protrusions shall not exceed 0.20mm (0.0078 inch) per side.
- 5. The chamfer on the body is optional. If it is not present, a visual index feature must be located within the crosshatched area.
- 6. "L" is the length of terminal for soldering to a substrate.
- 7. "N" is the number of terminal positions.
- 8. Terminal numbers are shown for reference only.
- Dimension "B" does not include dambar protrusion. Allowable dambar protrusion shall be 0.13mm (0.005 inch) total in excess of "B" dimension at maximum material condition.
- Controlling dimension: MILLIMETER. Converted inch dimensions are not necessarily exact.

M20.209 (JEDEC MO-150-AE ISSUE B)
20 LEAD SHRINK SMALL OUTLINE PLASTIC PACKAGE

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	INCHES		MILLIMETERS		
SYMBOL	MIN	MAX	MIN	MAX	NOTES
Α	0.068	0.078	1.73	1.99	
A1	0.002	0.008'	0.05	0.21	
A2	0.066	0.070'	1.68	1.78	
В	0.010'	0.015	0.25	0.38	9
С	0.004	0.008	0.09	0.20'	
D	0.278	0.289	7.07	7.33	3
Е	0.205	0.212	5.20'	5.38	4
е	0.026 BSC		0.65 BSC		
Н	0.301	0.311	7.65	7.90'	
L	0.025	0.037	0.63	0.95	6
N	20		20		7
α	0 deg.	8 deg.	0 deg.	8 deg.	

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